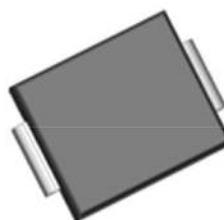


## **Features**

- Schottky barrier diodes
- Low forward voltage drop
- High Junction Temperature
- Moisture sensitivity: level 1, per J-STD-020
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Add suffix "E" for Halogen Free
- Halogen-free according to IEC 61249-2-21 definition



DO-214AB (SMC)

## **Typical Applications**

For use in low voltage, high frequency inverters, free wheeling, and polarity protection application

| <b>Maximum Ratings</b> (TA = 25 °C unless otherwise noted)                         |                                   |                 |      |
|--|-----------------------------------|-----------------|------|
| Parameter  | Symbol                            | SK5C0<br>SK5C0E | Unit |
| Maximum repetitive peak reverse voltage  | V <sub>RRM</sub>                  | 200             | V    |
| Maximum RMS voltage  | V <sub>RMS</sub>                  | 140             | V    |
| Maximum DC blocking voltage  | V <sub>DC</sub>                   | 200             | V    |
| Maximum average forward rectified current  | I <sub>F(AV)</sub>                | 5.0             | A    |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | I <sub>FSM</sub>                  | 120             | A    |
| Operating junction and storage temperature range                                   | T <sub>J</sub> , T <sub>STG</sub> | - 55 to + 150   | °C   |

| <b>Electrical Characteristics</b> (TA = 25 °C unless otherwise noted) |  |                |                 |      |
|---|--|----------------|-----------------|------|
| Parameter   | Test Conditions                          | Symbol         | SK5C0<br>SK5C0E | Unit |
| Maximum instantaneous forward voltage                                 | I <sub>F</sub> =5A, T <sub>A</sub> =25°C | V <sub>F</sub> | 0.85            | V    |
| Maximum DC reverse current at rated DC blocking voltage               | T <sub>A</sub> =25°C                     | I <sub>R</sub> | 30              | uA   |
|   | T <sub>A</sub> =125°C                    |                | 1000            |      |
| Typical junction capacitance  | 4.0 V, 1 MHz                             | C <sub>J</sub> | 96              | pF   |

| <b>Thermal Characteristics</b>            |                  |                 |      |  |
|---|------------------|-----------------|------|--|
| Parameter                                 | Symbol           | SK5C0<br>SK5C0E | Unit |  |
| Typical thermal resistance <sup>(1)</sup> | R <sub>θJA</sub> | 65              | °C/W |  |
|   | R <sub>θJC</sub> | 25              |      |  |
|   | R <sub>θJL</sub> | 15              |      |  |

Note1: Thermal resistance from junction to lead, mounted on PCB with 8.0×8.0mm copper pads

## Ratings and Characteristics Curves

(TA = 25°C unless otherwise noted)

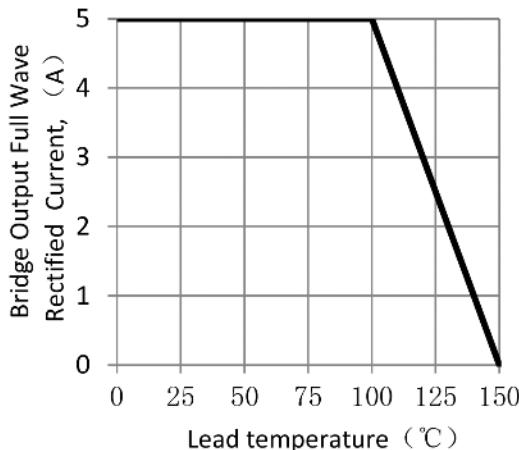


Figure 1. Forward Current Derating Curve

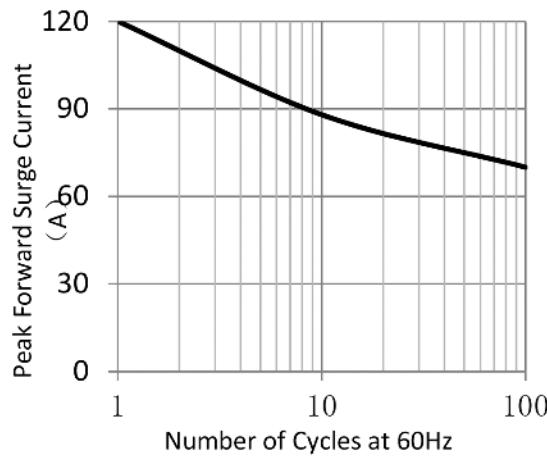


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

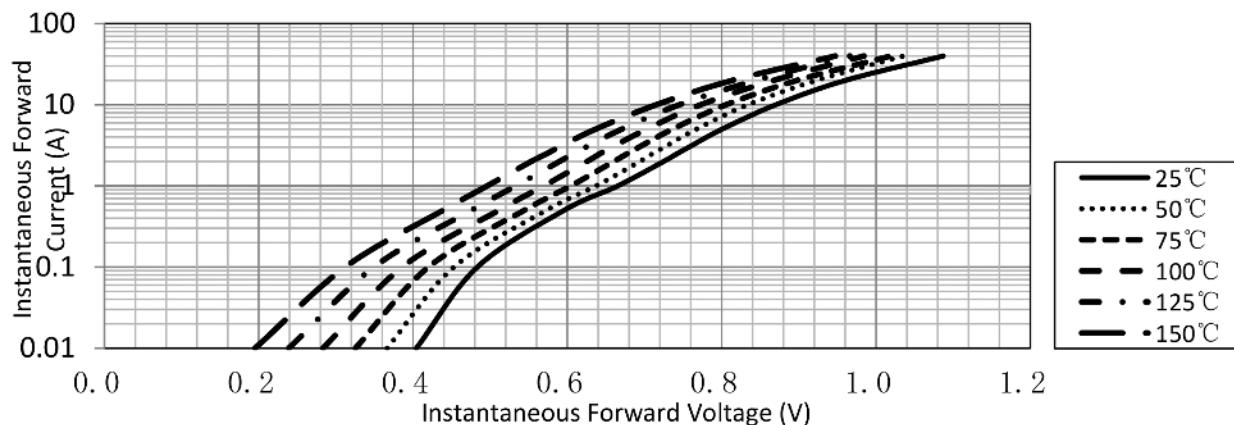


Figure 3. Typical Instantaneous Forward Characteristics

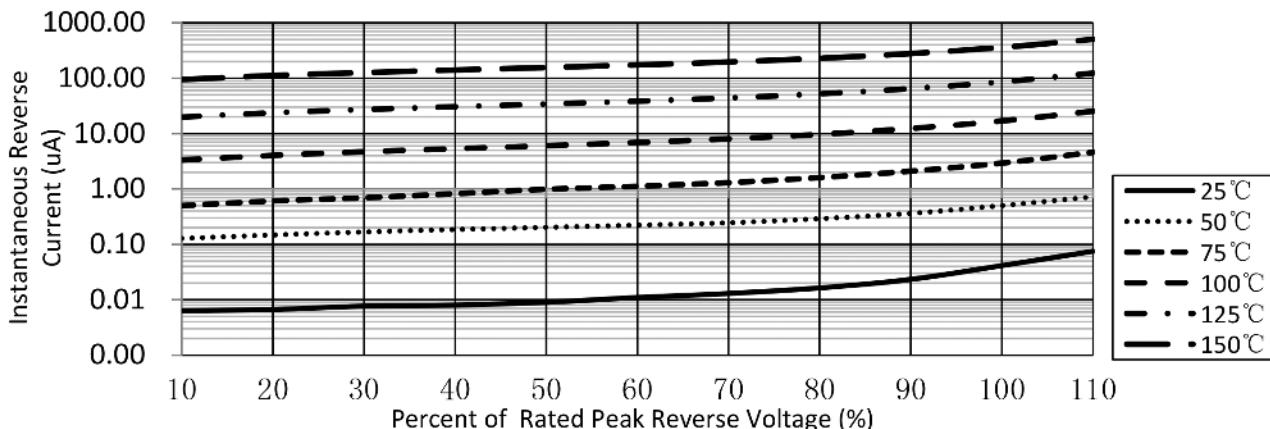
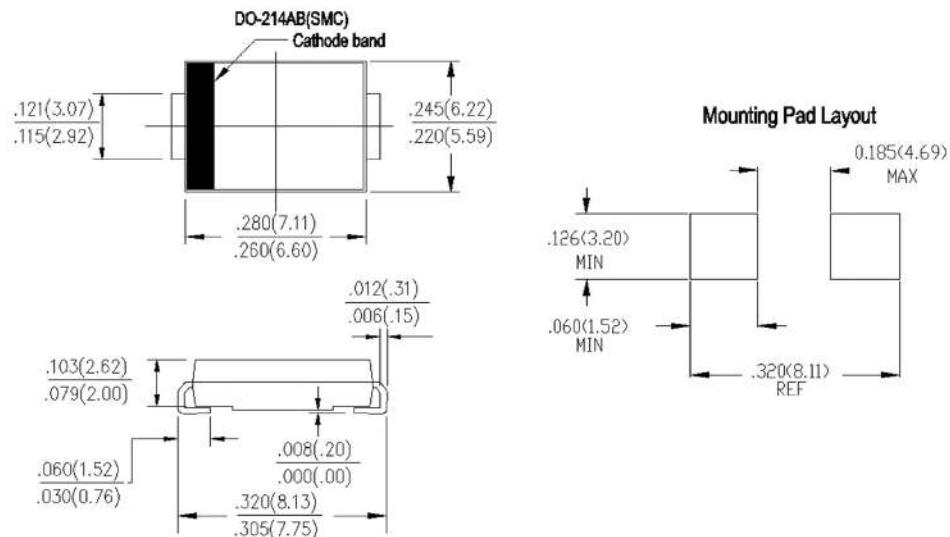


Figure 4. Typical Reverse Characteristics

## **Package Outline Dimensions**

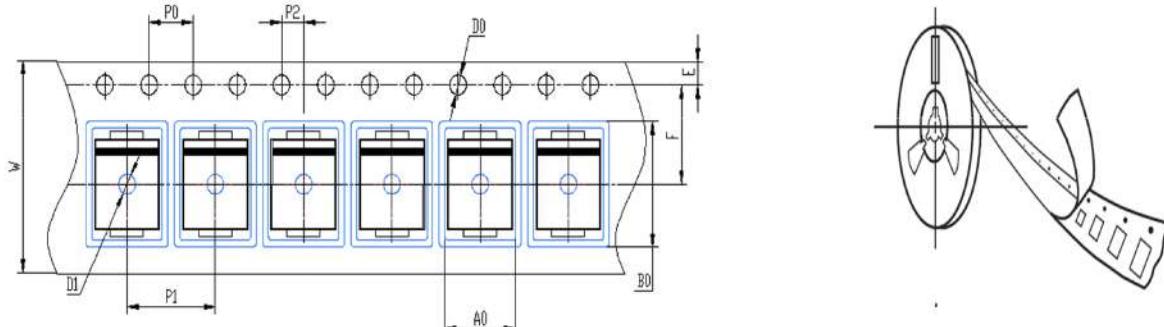
in inches (millimeters)



## **Packing Information**

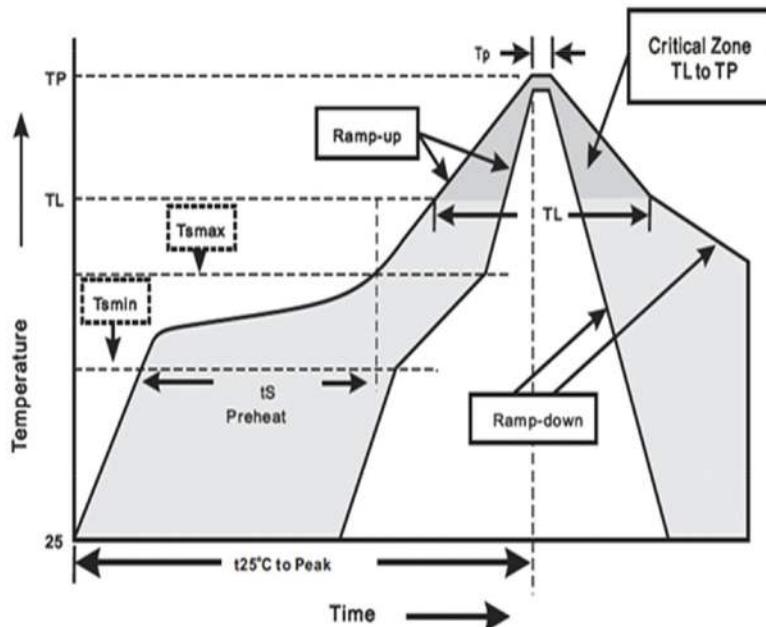
3000 pcs/Reel, 14 Reels/Box; 16mm Tape, 13" Reel

### Tape & Reel Specification



| Symbol | SMC (mm)       |
|--------|----------------|
| W      | $16 \pm 0.2$   |
| E      | $1.75 \pm 0.1$ |
| F      | $7.5 \pm 0.05$ |
| D0     | $1.5 \pm 0.1$  |
| D1     | $1.50 +0.1/-0$ |
| P0     | $4.0 \pm 0.1$  |
| P1     | $8.0 \pm 0.1$  |
| P2     | $2.0 \pm 0.05$ |
| A0     | $6.22 \pm 0.1$ |
| B0     | $8.31 \pm 0.1$ |

## Soldering Parameters



| Reflow Soldering                                  |                               | Sn-Pb Eutectic Assembly | Pb-Free assembly |
|---|-------------------------------|-------------------------|------------------|
| Pre Heat  | - Temperature Min (Ts(min))   | 100°C                   | 150°C            |
|   | - Temperature Max (Ts(max))   | 150°C                   | 200°C            |
|   | - Time (min to max) (ts)      | 60 – 120 secs           | 60 – 180 secs    |
| Average ramp up rate (Liquidus) Temp (TL) to peak |                               | 3°C/second max          | 3°C/second max   |
| TS(max) to TL - Ramp-up Rate                      |                               | 3°C/second max          | 3°C/second max   |
| Reflow  | - Temperature (TL) (Liquidus) | 183°C                   | 217°C            |
|   | - Time (min to max) (ts)      | 60 – 150 seconds        | 60 – 150 seconds |
| Peak Temperature (TP)                             |                               | 240+0/-5 °C             | 240+0/-5°C       |
| Time within 5°C of actual peak Temperature (tp)   |                               | 10 – 30 seconds         | 20 – 40 seconds  |
| Ramp-down Rate                                    |                               | 6°C/second max          | 6°C/second max   |
| Time 25°C to peak Temperature (TP)                |                               | 6 minutes Max.          | 8 minutes Max.   |
| Do not exceed                                     |                               | 260°C                   | 260°C            |

| Wave Soldering     |            |
|--------------------|------------|
| Peak Temperature : | 260+0/-5°C |
| Dipping Time :     | 10 seconds |
| Soldering :        | 1 time     |